



Product Change Notification: ALAN-08XQQK189

Date:

17-Sep-2024

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 32-Bit Microcontrollers, 8-Bit Microcontrollers

Notification Subject:

CCB 7116 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material for selected DSPIC33xx, PIC24EPxx, PIC32MXxx, PIC24FJxx, and PIC18F9xx device families available in 100L TQFP (12x12x1mm) package at MTAI assembly site.

Affected CPNs:

[ALAN-08XQQK189_Affected_CPN_09172024.pdf](#)

[ALAN-08XQQK189_Affected_CPN_09172024.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material for selected DSPIC33xx, PIC24EPxx, PIC32MXxx, PIC24FJxx, and PIC18F9xx device families available in 100L TQFP (12x12x1mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	Au	Au	CuPdAu
Die Attach Material	3280	3280	QMI519
Molding Compound Material	G700HA	G700HA	G700HA
Lead-Frame Material	C7025	C7025	C7025

*CPNs with Au as an existing wire material

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	CuPdAu	CuPdAu	CuPdAu
Die Attach Material	3280	3280	QMI519
Molding Compound Material	G700HA	G700HA	G700HA
Lead-Frame Material	C7025	C7025	C7025

*CPNs with CuPdAu as an existing wire material

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:October 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	September 2024				October 2024				
Workweek	36	37	38	39	40	41	42	43	44
Initial PCN Issue Date			X						
Qual Report Availability					X				
Final PCN Issue Date					X				

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:September 17, 2024: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ALAN-08XQQK189 Qual Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

DSPIC33EP512GM710-H/PT
DSPIC33EP256MU810-E/PT
DSPIC33EP512MU810-E/PT
DSPIC33EP256MU810-I/PT
DSPIC33EP512MU810-I/PT
DSPIC33EP256MU810T-I/PTC02
DSPIC33EP256MU810T-I/PT
DSPIC33EP512MU810T-I/PT
DSPIC33EP256MU810T-E/PT
DSPIC33EP512MU810T-E/PT
PIC24EP256GU810-E/PT
PIC24EP512GU810-E/PT
PIC24EP256GU810-I/PT
PIC24EP512GU810-I/PT
PIC24EP256GU810T-I/PT
PIC24EP512GU810T-I/PT
PIC24EP256GU810T-E/PT
PIC24EP512GU810T-E/PT
PIC32MX695F512L-80I/PT020
PIC32MX695F512L-80I/PT021
PIC32MX695F512L-80I/PT023
PIC32MX575F512L-80I/PT024
PIC32MX575F512L-80I/PT025
PIC32MX575F512L-80I/PTC21
PIC32MX575F512L-80I/PT
PIC32MX575F256L-80I/PT
PIC32MX695F512L-80I/PTD21
PIC32MX695F512L-80I/PTD22
PIC32MX695F512L-80I/PT
PIC32MX675F512L-80I/PT
PIC32MX675F256L-80I/PT
PIC32MX795F512L-80I/PTE22
PIC32MX795F512L-80I/PT
PIC32MX775F512L-80I/PT
PIC32MX775F256L-80I/PT
PIC32MX575F512L-80V/PTC22
PIC32MX575F512L-80V/PT
PIC32MX575F256L-80V/PT
PIC32MX695F512L-80V/PT
PIC32MX675F512L-80V/PT
PIC32MX675F256L-80V/PT
PIC32MX795F512L-80V/PT
PIC32MX775F512L-80V/PT
PIC32MX775F256L-80V/PT
PIC32MX575F512LT-80V/PTC22
PIC32MX575F512LT-80V/PT

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PIC32MX695F512LT-80V/PT
PIC32MX675F512LT-80V/PT
PIC32MX675F256LT-80V/PT
PIC32MX795F512LT-80V/PT
PIC32MX775F512LT-80V/PT
PIC32MX775F256LT-80V/PT
PIC32MX575F512LT-80I/PT024
PIC32MX575F512LT-80I/PT025
PIC32MX575F512LT-80I/PT
PIC32MX575F256LT-80I/PT
PIC32MX695F512LT-80I/PTD21
PIC32MX695F512LT-80I/PTD22
PIC32MX695F512LT-80I/PT
PIC32MX675F512LT-80I/PT
PIC32MX675F256LT-80I/PT
PIC32MX795F512LT-80I/PTE21
PIC32MX795F512LT-80I/PTE22
PIC32MX795F512LT-80I/PT
PIC32MX775F512LT-80I/PT
PIC32MX775F256LT-80I/PT
PIC24FJ256GB210-I/PT
PIC24FJ256GB210T-I/PT
PIC32MX564F128L-I/PT
PIC32MX534F064L-I/PT
PIC32MX564F064L-I/PT
PIC32MX664F128L-I/PT
PIC32MX664F064L-I/PT
PIC32MX764F128L-I/PT
PIC32MX564F128L-V/PT
PIC32MX534F064L-V/PT
PIC32MX564F064L-V/PT
PIC32MX664F128L-V/PT
PIC32MX664F064L-V/PT
PIC32MX764F128L-V/PT
PIC32MX564F128LT-V/PT
PIC32MX534F064LT-V/PT
PIC32MX564F064LT-V/PT
PIC32MX664F128LT-V/PT
PIC32MX664F064LT-V/PT
PIC32MX764F128LT-V/PT
PIC32MX564F128LT-I/PT
PIC32MX534F064LT-I/PT
PIC32MX564F064LT-I/PT
PIC32MX664F128LT-I/PT
PIC32MX664F064LT-I/PT
PIC32MX764F128LT-I/PT
PIC24FJ128GB210-I/PT
PIC24FJ128DA210-I/PT

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PIC24FJ256DA210-I/PTREL
PIC24FJ256DA210T-I/PT
PIC24FJ128DA110-I/PT
PIC24FJ256DA110-I/PT
PIC32MX450F256L-I/PT
PIC32MX450F128L-I/PT
PIC32MX450F256L-V/PT
PIC32MX450F128L-V/PT
PIC32MX450F256LT-V/PT
PIC32MX450F128LT-V/PT
PIC32MX450F256LT-I/PT
PIC32MX450F128LT-I/PT
PIC32MX350F256L-I/PT
PIC32MX350F128L-I/PT
PIC32MX350F256L-V/PT
PIC32MX350F128L-V/PT
PIC32MX350F256LT-V/PT
PIC32MX350F128LT-V/PT
PIC32MX350F256LT-I/PT
PIC32MX350F128LT-I/PT
PIC32MX150F256L-50I/PT
PIC32MX170F512L-50I/PT
PIC32MX130F128L-50I/PT
PIC32MX150F256LT-50I/PT
PIC32MX170F512LT-50I/PT
PIC32MX130F128LT-50I/PT
PIC32MX150F256L-I/PT
PIC32MX170F512L-I/PT
PIC32MX130F128L-I/PT
PIC32MX150F256L-V/PT
PIC32MX170F512L-V/PT
PIC32MX130F128L-V/PT
PIC32MX150F256LT-V/PT
PIC32MX170F512LT-V/PT
PIC32MX130F128LT-V/PT
PIC32MX150F256LT-I/PT
PIC32MX170F512LT-I/PT
PIC32MX130F128LT-I/PT
PIC32MX250F256L-I/PT
PIC32MX230F128L-I/PT
PIC32MX270F512L-I/PT
PIC32MX550F256L-I/PT
PIC32MX530F128L-I/PT
PIC32MX570F512L-I/PT
PIC32MX250F256L-V/PT
PIC32MX230F128L-V/PT
PIC32MX270F512L-V/PT
PIC32MX550F256L-V/PT

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PIC32MX570F512L-V/PT
PIC32MX250F256LT-V/PT
PIC32MX230F128LT-V/PT
PIC32MX270F512LT-V/PT
PIC32MX550F256LT-V/PT
PIC32MX530F128LT-V/PT
PIC32MX570F512LT-V/PT
PIC32MX250F256LT-I/PT
PIC32MX230F128LT-I/PT
PIC32MX270F512LT-I/PT
PIC32MX550F256LT-I/PT
PIC32MX530F128LT-I/PT
PIC32MX570F512LT-I/PT
PIC32MX250F256L-50I/PT
PIC32MX230F128L-50I/PT
PIC32MX270F512L-50I/PT
PIC32MX550F256L-50I/PT
PIC32MX530F128L-50I/PT
PIC32MX570F512L-50I/PT
PIC32MX250F256LT-50I/PT
PIC32MX230F128LT-50I/PT
PIC32MX270F512LT-50I/PT
PIC32MX550F256LT-50I/PT
PIC32MX530F128LT-50I/PT
PIC32MX570F512LT-50I/PT
PIC18F96J94-I/PT
PIC18F97J94-I/PT
PIC18F97J94T-I/PT
PIC18F95J94-I/PT
PIC18F95J94T-I/PT
DSPIC33EP128GM710-E/PT
DSPIC33EP256GM710-E/PT
DSPIC33EP512GM710-E/PT
DSPIC33EP128GM310-I/PT
DSPIC33EP128GM710-I/PT
DSPIC33EP256GM310-I/PT
DSPIC33EP256GM710-I/PT
DSPIC33EP512GM310-I/PT
DSPIC33EP512GM710-I/PT
DSPIC33EP256GM310T-I/PT
DSPIC33EP256GM710T-I/PT
DSPIC33EP512GM310T-I/PT
PIC32MX470F512L-120/PT021
PIC32MX470F512L-120/PT
PIC32MX470F512LT-120/PT022
PIC32MX470F512LT-120/PT
PIC32MX370F512L-I/PT
PIC32MX370F512L-V/PT

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PIC32MX370F512LT-I/PT
PIC32MX470F512L-I/PT
PIC32MX470F512L-V/PT
PIC32MX470F512LT-V/PT
PIC32MX470F512LT-I/PT021
PIC32MX470F512LT-I/PT022
PIC32MX470F512LT-I/PT
PIC24FJ128GC010-I/PT
PIC24FJ128GC010T-I/PT
PIC24FJ256GA410-I/PT
PIC24FJ128GA410-I/PT
PIC24FJ64GA410-I/PT
PIC24FJ256GA410T-I/PT
PIC24FJ128GA410T-I/PT
PIC24FJ64GA410T-I/PT
PIC24FJ256GB410-I/PT
PIC24FJ128GB410-I/PT
PIC24FJ64GB410-I/PT
PIC24FJ256GB410T-I/PT
PIC24FJ128GB410T-I/PT
PIC24FJ64GB410T-I/PT
PIC32MX430F064L-I/PT
PIC32MX430F064L-V/PT
PIC32MX430F064LT-V/PT
PIC32MX430F064LT-I/PT
PIC24FJ128GA310-I/PTREL
PIC24FJ128GA310-I/PT
PIC24FJ128GA310-I/PTC04
PIC24FJ128GA310T-I/PT
PIC24FJ64GA310-I/PTREL
PIC24FJ64GA310-I/PT
PIC24FJ64GA310T-I/PT
PIC24FJ64GC010-I/PT
PIC32MX330F064L-I/PT
PIC32MX330F064L-V/PT
PIC32MX330F064LT-V/PT
PIC32MX330F064LT-I/PT
PIC32MX450F256L-120/PT
PIC32MX450F256LT-120/PT